

MRF24WG0MA/MB Data Sheet 2.4 GHz IEEE 802.11b/gTM

Features:

- IEEE 802.11-compliant RF transceiver
- · Serialized unique MAC address
- Data rate: 1 to 11 Mbps for 802.11b / 6 to 54 Mbps for 802.11g
- · Compatible with IEEE 802.11b/g/n networks
- Small size: 21 mm x 31 mm 36-pin Surface Mount module
- Integrated PCB antenna (MRF24WG0MA)
- External antenna option (MRF24WG0MB) with ultra-miniature coaxial (U.FL) connector
- Easy integration into final product accelerates product development, provides quicker time to market
- Radio regulation certification for United States (FCC), Canada (IC), and Europe (ETSI)
- Designed for use with Microchip microcontroller families (PIC18, PIC24, dsPIC33, and PIC32) with downloadable Microchip TCP/IP Stack

Operational:

- Single operating voltage: 2.8V to 3.6V (3.3V typical)
 - Temperature range: -40°C to +85°C
 - · Simple, four-wire SPI interface with interrupt
 - Low-current consumption:
 - RX mode 95 mA (typical)
 - TX mode 240 mA (+18 dBm typical)
 - PS mode 4 mA (typical)
 - Hibernate mode 0.1 mA (typical)

RF/Analog Features:

- ISM Band 2.400 to 2.484 GHz operation
- 14 Channels selectable individually or domainrestricted
- · DSSS/OFDM modulation
- · Application throughput: 4500 kbps
- -95 dBm Typical sensitivity at 1 Mbps
- +18 dBm Typical 802.11b TX power with control
- +16 dBm Typical 802.11g TX power with control
- Integrated low phase noise VCO, RF frequency synthesizer, PLL loop filter and PA
- Integrated RSSI ADC and I/Q DACs, RSSI readings available to host

MAC/Baseband Features:

- Hardware CSMA/CA access control, automatic ACK, and FCS creation and checking
- · Automatic MAC packet retransmit
- Hardware Security Engine for AES and RC4-based ciphers
- Supports 802.1x, 802.1i security: WEP, WPA-PSK, and WPA-2-PSK.

Applications:

- · Utility and Smart Energy:
 - Thermostats
 - Smart Meters
 - White Goods
 - HVAC
- · Consumer Electronics:
 - Remote Control
 - Internet Radio
 - Home Security
 - Toys
- Industrial Controls:
 - Chemical Sensors
 - HVAC
 - Security Systems
 - M2M Communication
- · Remote Device Management:
 - Location and Asset Tracking
 - Automotive
 - Code Update
- · Retail:
 - POS Terminals
 - Wireless Price Tags
 - Digital Remote
- · Medical, Fitness, and Health Care:
 - Glucose Meters
 - Fitness Equipment
 - Patient Asset Tracking

Pin Diagram **GND** 1 36 **GND** 234567 35 SDI NC NC* 34 SCK NC* 33 INT NC* 32 SDO NC* 31 NC RESET 30 **GND** 89 NC NC* 29 **VDD** 28 **GND** 10 27 DEBUG_TX **GND** 26 DEBUG_RX 11 NC 12 NC **GND** NC 13 24 NC CS 14 NC 23 22 NC 15 NC $\overline{\mathsf{WP}}$ NC* 16 21 20 **HIBERNATE VDD** 17 **GND** 18 19 **GND**

Note:

Antenna connector on MRF24WG0MB only.

Table of Contents

1.0	Device Overview	5
	Circuit Description	
3.0	Regulatory Approval	21
4.0	Electrical Characteristics	27
	endix A: Revision History	
The	Microchip Web Site	33
	omer Change Notification Service	
Cust	omer Support	33
	der Response	
Prod	uct Identification System	35

TO OUR VALUED CUSTOMERS

It is our intention to provide our valued customers with the best documentation possible to ensure successful use of your Microchip products. To this end, we will continue to improve our publications to better suit your needs. Our publications will be refined and enhanced as new volumes and updates are introduced.

If you have any questions or comments regarding this publication, please contact the Marketing Communications Department via E-mail at **docerrors@microchip.com** or fax the **Reader Response Form** in the back of this data sheet to (480) 792-4150. We welcome your feedback.

Most Current Data Sheet

To obtain the most up-to-date version of this data sheet, please register at our Worldwide Web site at:

http://www.microchip.com

You can determine the version of a data sheet by examining its literature number found on the bottom outside corner of any page. The last character of the literature number is the version number, (e.g., DS30000A is version A of document DS30000).

Errata

An errata sheet, describing minor operational differences from the data sheet and recommended workarounds, may exist for current devices. As device/documentation issues become known to us, we will publish an errata sheet. The errata will specify the revision of silicon and revision of document to which it applies.

To determine if an errata sheet exists for a particular device, please check with one of the following:

- Microchip's Worldwide Web site; http://www.microchip.com
- Your local Microchip sales office (see last page)

When contacting a sales office, please specify which device, revision of silicon and data sheet (include literature number) you are using.

Customer Notification System

Register on our web site at www.microchip.com to receive the most current information on all of our products.

NOTES:

1.0 DEVICE OVERVIEW

The MRF24WG0MA and MRF24WG0MB are low-power, 2.4 GHz, IEEE 802.11-compliant, surface mount modules with all associated RF components – crystal oscillator, bypass and bias passives with integrated MAC, baseband, RF and power amplifier, and built-in hardware support for AES, and TKIP (WEP, WPA, WPA2 security). The modules also provide acceleration for hosts running WPA-EAP application security. The integrated module design frees the designer from RF and antenna design tasks and regulatory compliance testing, ultimately providing quicker time to market.

The MRF24WG0MA module is approved for use with the integrated PCB meander antenna.

The MRF24WG0MB module comes with an ultraminiature coaxial connector (U.FL) and is approved for use with a list of antenna types that are certified with the module. See **Section 2.7** "External Antenna" for specific recommendations.

The MRF24WG0MA/MB modules are designed to be used with Microchip's TCP/IP software stack. The software stack has an integrated driver that implements the API that is used in the modules for command and control, and for management and data packet traffic.

The Microchip TCP/IP software stack is available in the free *Microchip Application Libraries* download (including example applications and source code) from the Microchip web site, http://www.microchip.com/wireless.

The combination of the module and a PIC running the TCP/IP stack results in support for IEEE Standard 802.11 and IP services. For example, this allows the immediate implementation of a wireless web server and e-mail clients.

The MRF24WG0MA/MB modules have received regulatory approvals for modular devices in the United States (FCC), Canada (IC), and Europe (ETSI). The modular approval removes the need for expensive RF and antenna design, and allows the end user to place the modules inside a finished product and not require regulatory testing for an intentional radiator (RF transmitter). See **Section 3.0** "Regulatory Approval", for the specific requirements that should be adhered to by the integrator.

1.1 Interface Description

The block diagram in Figure 1-1 represents a MRF24WG0MA/MB module. It interfaces to Microchip PIC18, PIC24, dsPIC33, or PIC32 microcontrollers through a four-wire serial slave SPI interface – interrupt, hibernate, reset, power and ground signals. The module runs on a single supply voltage of nominally 3.3V. The serial trace port operates at 3.3V and requires a level shifter for operation with RS-232 devices. This port provides a serial output of module status messages and is helpful for debugging purposes. Figure 1-2 shows a simplified example connection between a Microchip PIC MCU and the module. Table 1-1 lists the pin descriptions.

Data communications with the MRF24WG0MA/MB are through the SPI interface that is detailed in **Section 2.0** "Circuit Description". The Microchip PIC microcontroller communicates with the module through a command API from within the Microchip TCP/IP stack. The command API is detailed in the Microchip TCP/IP stack online Help that is included in the free *Microchip Application Libraries* download.

FIGURE 1-1: MRF24WG0MA/MB BLOCK DIAGRAM

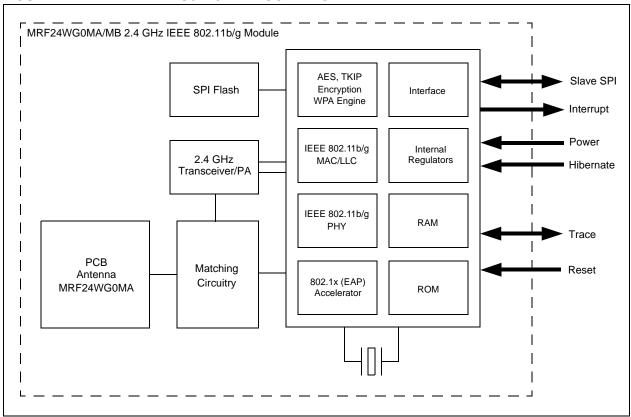


FIGURE 1-2: MICROCONTROLLER TO MRF24WG0MA/MB INTERFACE

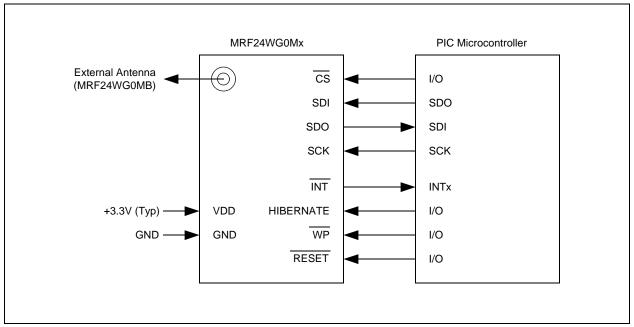


TABLE 1-1: Pin Description

Pin	Symbol	Туре	Description
1	GND	Р	Ground
2	NC*	NC*	No connect ⁽³⁾
3	NC*	NC*	No connect ⁽³⁾
4	NC*	NC*	No connect ⁽³⁾
5	NC*	NC*	No connect ⁽³⁾
6	NC*	NC*	No connect ⁽³⁾
7	RESET	I: Constant ⁽¹⁾	Module Reset input
8	NC	NC	Do not connect
9	NC*	NC*	No connect ⁽³⁾
10	GND	Р	Ground
11	NC	NC	Do not connect
12	NC	NC	Do not connect
13	NC	NC	Do not connect
14	NC	NC	Do not connect
15	NC	NC	Do not connect
16	WP ⁽²⁾	I	Write protect (this pin is used to enable FLASH update)
17	Vdd	Р	Power
18	GND	Р	Ground
19	GND	Р	Ground
20	HIBERNATE	I	Hibernate mode enable (high input will disable the module)
21	NC*	NC*	No connect ⁽³⁾
22	NC	NC	Do not connect
23	CS	I: Constant ⁽¹⁾	SPI Chip Select input, constant drive or pull-up required
24	NC	NC	Do not connect
25	GND	Р	Ground
26	DEBUGRX	I	Serial debug port input (see Section 2.0 "Circuit Description")
27	DEBUGTX	0	Serial debug port output (see Section 2.0 "Circuit Description")
28	GND	Р	Ground
29	Vdd	Р	Power
30	GND	Р	Ground
31	NC	NC	Do not connect
32	SDO	0	SPI data out
33	ĪNT	0	Interrupt output (open drain – requires a pull-up)
34	SCK	I	SPI clock input
35	SDI	I	SPI data in
36	GND	Р	Ground

 $\textbf{Legend:} \quad \text{Pin type abbreviation: P = Power Input, I = Input, O = Output, NC = Do Not Connect, NC* = No Connect}$

- **Note 1:** Signals of Type "I: Constant" must either be constantly driven by the host or have a pull-up or pull-down (in case the host is likely to tri-state the signal during power down modes). The constant drive is used to ensure defined operation of the part and to minimize leakage current during low power modes.
 - **2:** WP is used as write-protect for the internal module SPI Flash. For production use, this pin should be pulled low. This pin can be controlled by the host microcontroller to enable in field Flash updates.
 - **3:** Signals of Type "NC*" were JTAG function pins on previous family devices. Signals on these pins will have no functional affect and will not impact the operation of this device.

1.2 Mounting Details

The MRF24WG0MA/MB is a surface mountable module. Module dimensions are shown in Figure 1-3. The module Printed Circuit Board (PCB) is 1 mm thick with castellated mounting points on two sides.

FIGURE 1-3: MRF24WG0MA/MB MODULE PHYSICAL DIMENSIONS

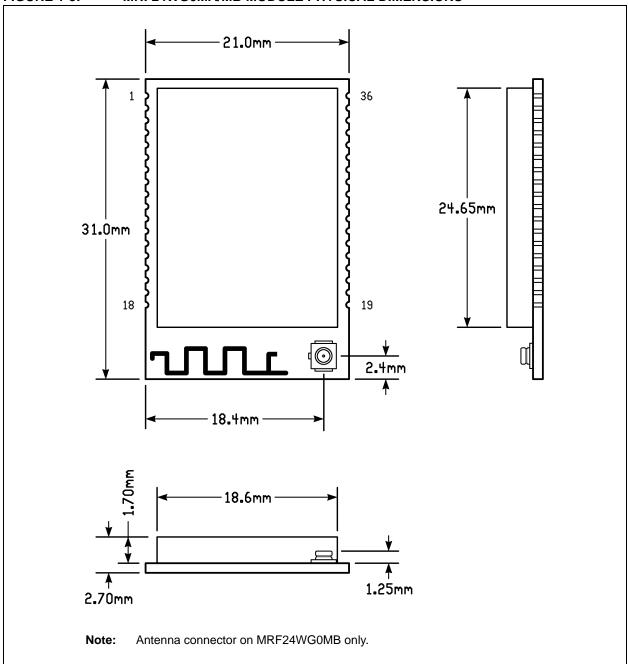
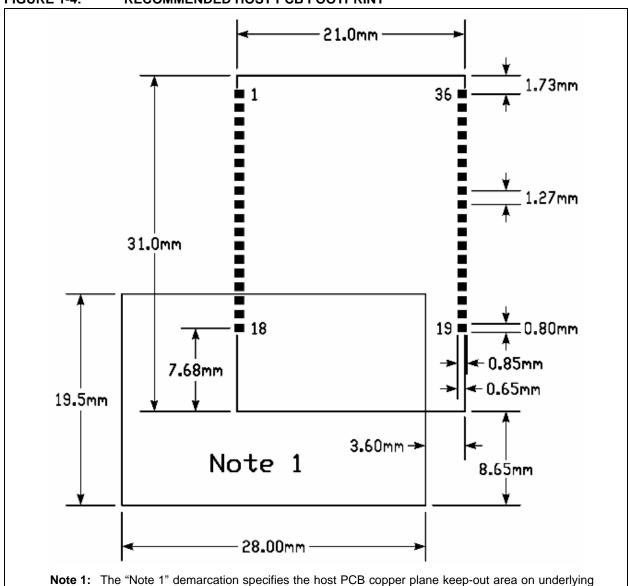


Figure 1-4 shows the recommended host PCB footprint for the module.

The MRF24WG0MA has an integrated PCB antenna. For best performance, follow the mounting details shown in Figure 1-4.

For best performance, mount the module on the PCB without metal obstructions in the keep out area of Figure 1-4. The antenna is tuned to have FR4 PCB material underneath the module. Do not "cut-out" host PCB material under the antenna.

FIGURE 1-4: RECOMMENDED HOST PCB FOOTPRINT



board layers. It is permissible to route surface escape traces in this area.

Figure 1-5 illustrates the module reflow profile that is recommended for mounting the device onto the host PCB.

FIGURE 1-5: PRELIMINARY MODULE REFLOW PROFILE AND SETPOINTS

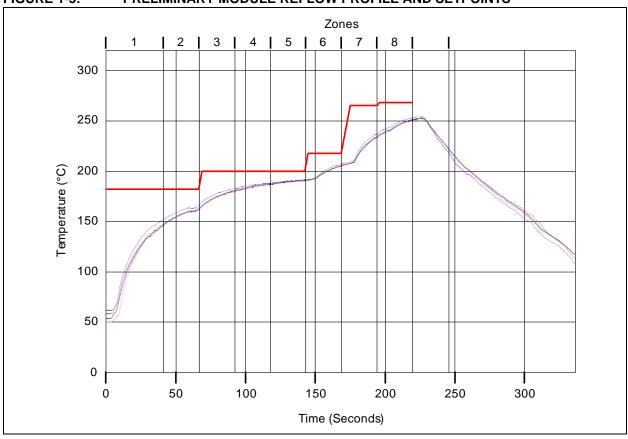


TABLE 1-2: MODULE REFLOW PROFILE⁽¹⁾

Zone	1	2	3	4	5	6	7	8
Temperature (°C)	180°	180°	200°	200°	200°	220°	265°	270°

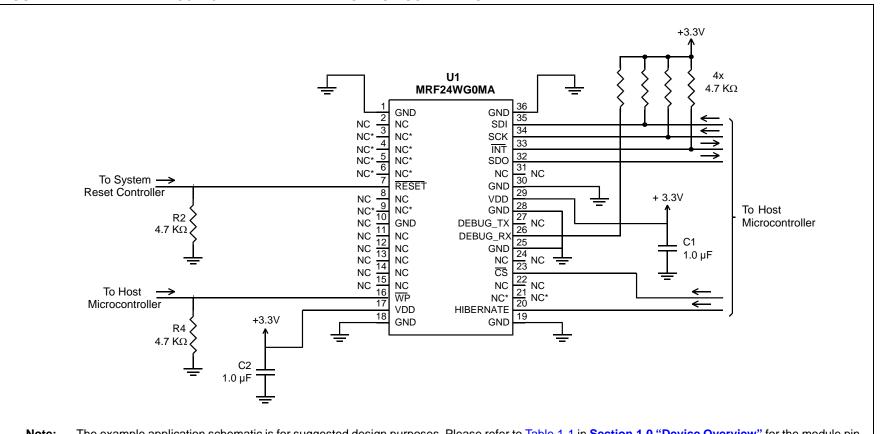
Note 1: Conveyor Speed: 90 cm/min

2.0 CIRCUIT DESCRIPTION

The MRF24WG0MA/MB interfaces to Microchip PIC18, PIC24, dsPIC33, and PIC32 microprocessors with a minimal of external components through digital-only connections. This section details use of the module, starting with an example host connection as shown in Figure 2-1.

2.1 Schematic

FIGURE 2-1: MRF24WG0MA/MB EXAMPLE APPLICATION SCHEMATIC



Note: The example application schematic is for suggested design purposes. Please refer to Table 1-1 in **Section 1.0 "Device Overview"** for the module pin descriptions.

MRF24WG0MA/MB

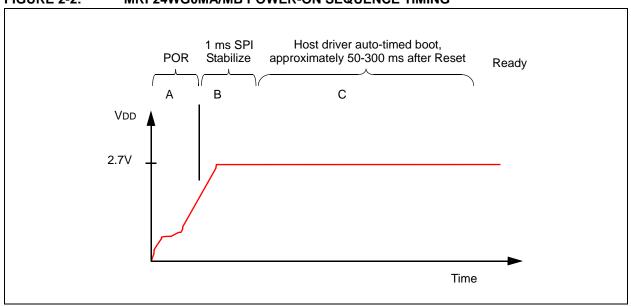
2.2 Power-On Sequence

The internal regulators for the digital and analog core power supplies are disabled by driving the HIBERNATE pin high. Figure 2-2 shows the power up sequence for the MRF24WG0MA/MB.

There is an internal Power-on-Reset (POR) circuit which keeps the module in reset until VDD is within specification. The Hibernate and Reset signals are also used to control startup. In Figure 2-2, section A is controlled by the internal POR and section B is an

allowance for the SPI bus to stabilize when the module supplies are enabled. Once Hibernate is disabled, the host software provides 1mS of startup to allow the SPI to stabilize. This time is pre-programmed into the host driver, and may need to be increased if sufficient initial drive current is not provided to the MRF24WG0MA/MB module. Section C is the driver controlled release from Reset period. This takes approximately 300 mS and is monitored by the stack driver. No additional time needs to be provided by user software for startup.

FIGURE 2-2: MRF24WG0MA/MB POWER-ON SEQUENCE TIMING



2.3 Power States

The MRF24WG0MA/MB has several power states. These are Hibernate, Sleep and Active (two substates), as shown in Figure 2-3. The selection of power state directly affects system behavior, and overall power consumption or battery life. There is also a "Stand-by" state that is not user-controlled.

2.3.1 HIBERNATE STATE

An "Off" state is defined as no power applied to the device. The Hibernate mode is the closest to controlled off that the module can approach. It is controlled through the HIBERNATE pin (high input puts the module into Hibernate). When in Hibernate, the module only consumes leakage current, but does not maintain state. Hibernate has to be fully controlled by the PIC MCU and requires the TCP/IP stack to restart on an awake.

The module contains about 70 μF of internal bulk capacitance. Supplies should be provisioned to supply sufficient charge on release of hibernate for desired start time or sufficient delay must be provided in software after hibernate release and before releasing reset.

This state provides the best battery life for embedded products. Entering Hibernate for intervals of less than 30 seconds is not likely to save power. Battery life expectation can be more than a year for devices operating on AA cells that would be in Hibernate except to wake up every hour for a small data transfer (<500 Bytes).

2.3.2 POWER SAVE (PS) MODE

The PS mode is a low-power dynamic state that automatically implements the 802.11 Power Save feature. In this mode, if enabled, the module will enter PS mode when all activity is complete.

The module will wake autonomously to any PIC intervention so it can check DTIM beacons from the Access Point. If any traffic is listed as queued for the module, then it will awaken and get the data from the Access Point on the next possible opportunity. When data is acquired, the module will interrupt the PIC microcontroller on a normal "data available" indication. If no data is available on a DTIM check, the module reenters the Power Save state until the next DTIM. The DTIM interval is programmed at the Access Point. This state can provide "as if on" behavior of the radio with a significant power savings versus "always on". The battery life expectation of this mode is several days to several weeks. This mode is characterized by a very low latency (as low as 200 ms) to begin data transfer from the state.

2.3.3 ACTIVE STATE

The Active state is identified as one of two states where the radio circuitry is fully on. The two active states are the Receive state (RX ON) and the Transmit state (TX ON).

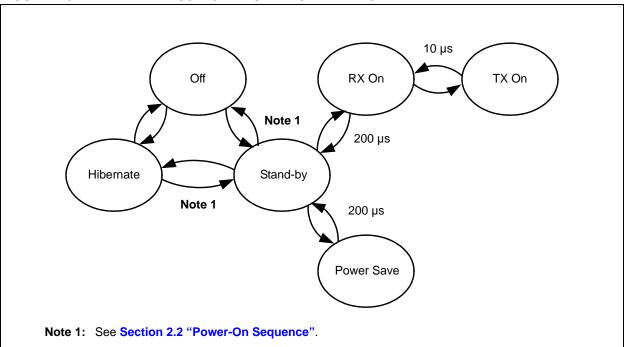
2.3.4 STAND-BY STATE

The Stand-by state is not user-controlled but is noted as it helps identify and track certain operations of the module during power tracing.

TABLE 2-1: MRF24WG0MA/MB POWER STATE DEFINITIONS

State	VDD	cs	Description
Off	0V	0V	Power is completely disconnected
Hibernate	3.3V	3.3V	All internal power regulators are OFF – enabled by HIBERNATE pin
Power Save	3.3V	0V	Enabled by TCP/IP driver
RX ON	3.3V	0V	Receive circuits are on and receiving
TX ON	3.3V	0V	Transmit circuits are on and transmitting
Stand-by	3.3V	0V	State machine transition state only – not user controlled

FIGURE 2-3: MRF24WG0MA/MB POWER-STATE DIAGRAM



2.4 Serial Trace Port Interface

The MRF24WG0MA/MB incorporates a Transmit Data pin (DEBUGTX) and a Receive Data pin (DEBUGRX) for serial debugging purposes. These pins can be connected to commercially available RS-232 line drivers/receivers with appropriate external level shifters. The serial interface operates at 19200, 8, N, 1, N.

2.5 SPI Interface

The slave Serial Peripheral Interface (SPI) is used to interface with the host PIC microcontroller. The slave SPI interface works with the Interrupt line (INT). When data is available for the PIC microcontroller during operation, the INT line is asserted (logic low) by the MRF24WG0MA/MB module. The INT line is deasserted (logic high) by the MRF24WG0MA/MB after the data is transferred to the host PIC microcontroller. The SPI SCK frequency can be up to 25 MHz.

The slave SPI interface implements the [CPOL = 0; CPHA = 0] and [CPOL = 1; CPHA = 1] modes (0 and 3) of operation. That is, data is clocked in on the first rising edge of the clock after Chip Select (CS) is asserted.

Data is placed on the bus with most significant bit (MSb) first.

The $\overline{\text{CS}}$ pin must be toggled with transfer blocks and cannot be held low permanently. The falling edge of $\overline{\text{CS}}$ is used to indicate the start of a transfer. The rising edge of $\overline{\text{CS}}$ is used to indicate the completion of a transfer.

Figure 4-1 in **Section 4.0** "**Electrical Characteristics**" shows the SPI timing diagram. Table 4-7 details the SPI timing AC characteristics.

2.6 PCB Antenna

For the MRF24WG0MA, the PCB antenna is fabricated on the top copper layer and covered in solder mask. The layers below the antenna have no copper trace.

It is recommended that the module be mounted on the edge of the host PCB. It is permitted for PCB material to be below the antenna structure of the module as long as no copper traces or planes are on the host PCB in that area. For best performance, place the module on the host PCB according to the details shown in Figure 1-4 in Section 1.0 "Device Overview".

The antenna patterns shown in the following plots are simulated results of the PCB antenna. Figure 2-4 illustrates the simulation drawing and Figure 2-5 and Figure 2-6 illustrate the two-dimensional (2D) and three-dimensional (3D) radiation patterns.

The calculated average of the radiated field is shown in Figure 2-5, highlighted in yellow. The radiation pattern for the XZ plane is shown in red, and the YZ plane is shown in black. As shown, the most powerful radiation occurs in the XY plane (the red pattern).

Figure 2-6 shows the relative position of the 3D radiation "donut" with reference to the module orientation. This is a very useful guide for placement of the module to obtain the maximum range.

Figure 2-7 shows the 3D radiation pattern with the colored distribution of the radiation magnitude. The values range from -9 dB to +0.3 dB. This is very useful in interpreting the 2D radiation pattern.



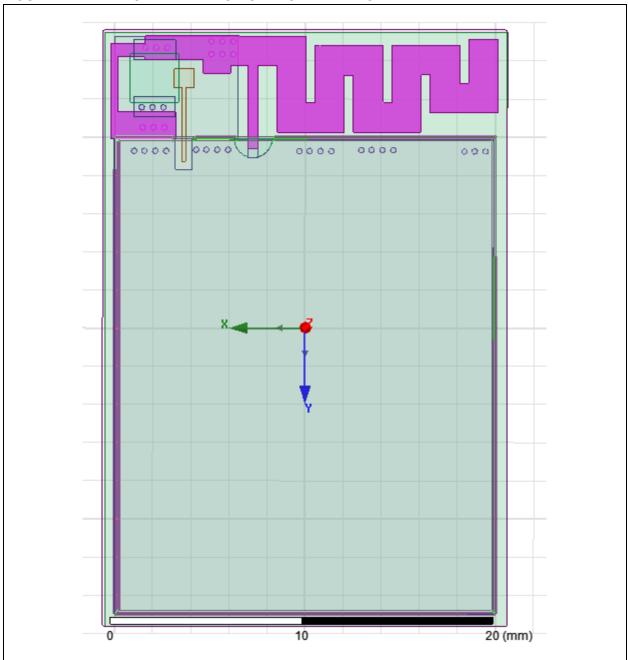
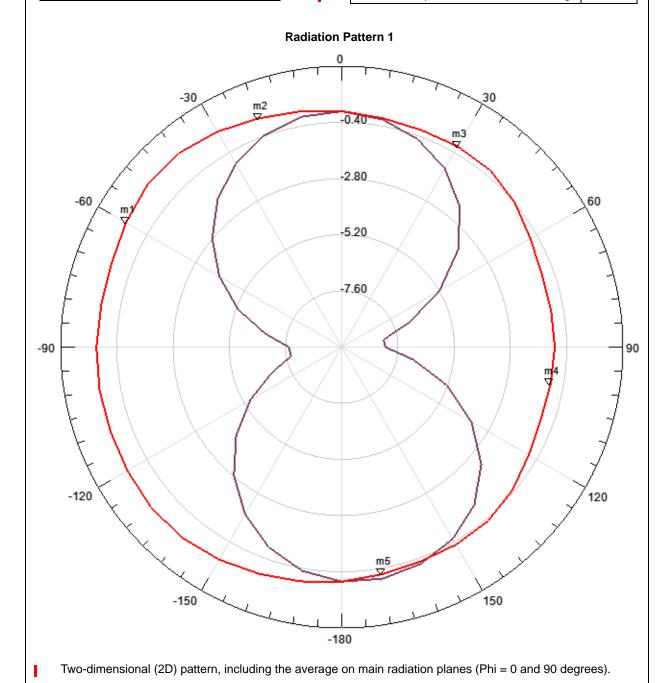
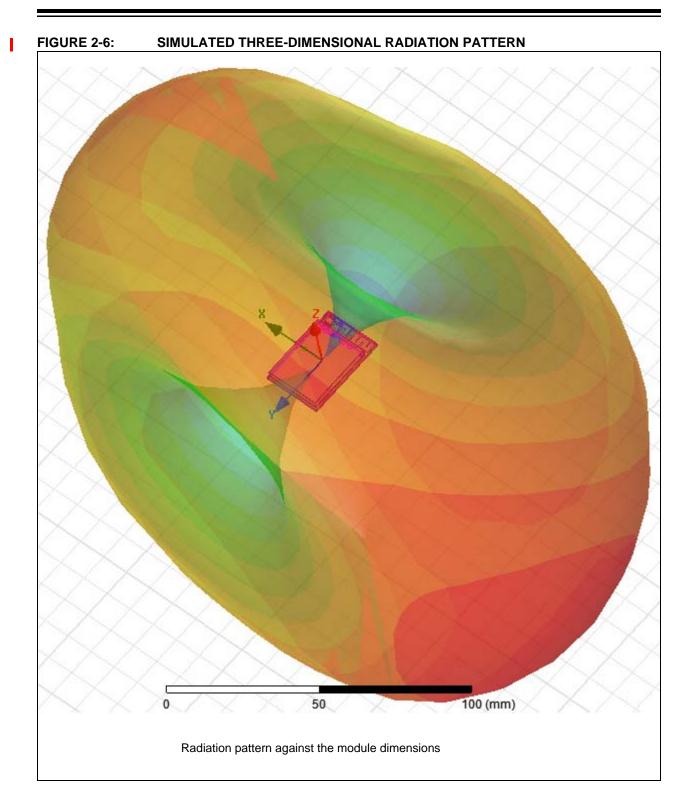


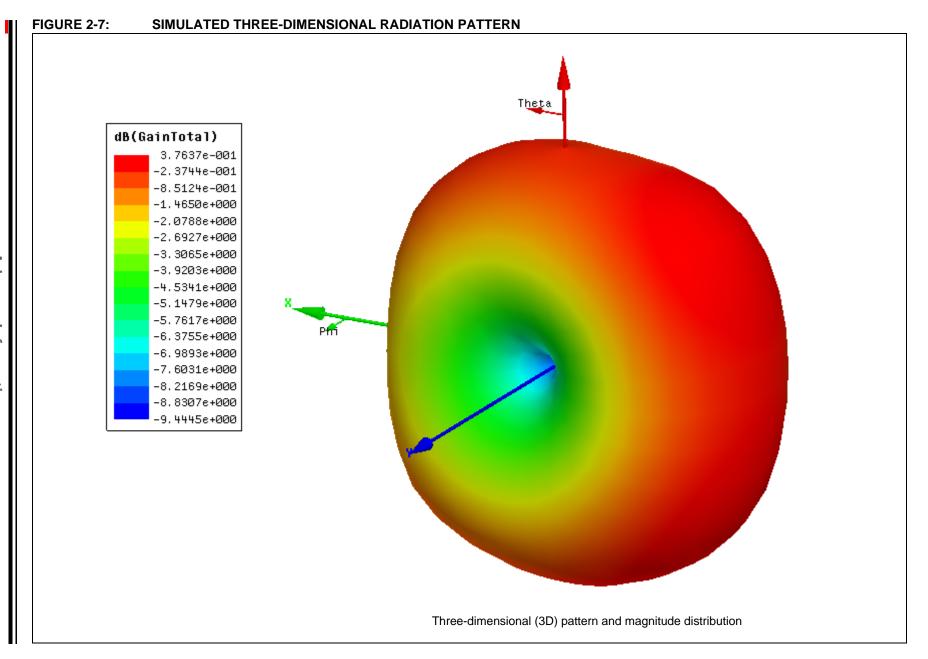
FIGURE 2-5: SIMULATED TWO-DIMENSIONAL RADIATION PATTERN

Name	Theta	Angle	Mag.
m1	-60.0000	-60.0000	0.6323
m2	-20.0000	-20.0000	0.3962
m3	30.0000	30.0000	-0.1038
m4	100.0000	100.0000	-0.9490
m5	170.0000	170.0000	-0.1414

Curve Information	Average
 db(GainTotal) Setup 1: LastAdaptive Freq. = "2.44 GHZ" Phi = "0 deg"	0.0097
 dB(GainTotal) Setup 2: LastAdaptive Freq. = "2.44 GHz" Phi = "0 deg"	-3.2020







2.7 External Antenna

The MRF24WG0MB module has a 50Ω ultra-miniature coaxial (U.FL) connector to connect to an external 2.4 GHz antenna.

Caution: The U.FL connector is fragile and can only tolerate a very limited number of insertions.

The choice of antenna is limited to the antenna types the module has been tested with. Refer to the respective country in **Section 3.0 "Regulatory Approval"** for a list of tested and approved antenna types that may be used with the MRF24WG0MB module.

A list of antennas approved for use with the module is provided in Table 2-2.

TABLE 2-2: APPROVED EXTERNAL ANTENNA TYPES

Туре	Manufacturer	Part Number	Gain
Dipole	Aristotle	RFA-02-C2M2-D034	2 dBi
PCB	Aristotle	RFA-02-P33-D034	1 dBi
PCB	Aristotle	RFA-02-P05-D034	2 dBi
PIFA	Aristotle	RFA-02-G03-D034	0 dBi

3.0 REGULATORY APPROVAL

The MRF24WG0MA/MB module has received regulatory approvals for modular devices in the United States and Canada. Modular approval allows the end user to place the MRF24WG0MA/MB module inside a finished product and not require regulatory testing for an intentional radiator (RF transmitter), provided no changes or modifications are made to the module circuitry. Changes or modifications could void the user's authority to operate the equipment. The end user must comply with all of the instructions provided by the Grantee, which indicate installation and/or operating conditions necessary for compliance.

The MRF24WG0MA/MB module has been tested and conforms to EN 300 328 V1.7.1 (2006-10), European Standards. The module tests can be applied toward final product certification and Declaration of Conformity (DoC). Additional testing may be required depending on the end application.

The integrator may still be responsible for testing the end product for any additional compliance requirements that become necessary with this module installed (for example, digital device emission, PC peripheral requirements, etc.) in the specific country that the end device will be marketed.

For more information on regulatory compliance, refer to the specific country radio regulations in the following sections.

3.1 United States

The MRF24WG0MA/MB has received Federal Communications Commission (FCC) CFR47 Telecommunications, Part 15 Subpart C "Intentional Radiators" 15.247 and modular approval in accordance with Part 15.212 Modular Transmitter approval. The MRF24WG0MA/MB module can be integrated into a finished product without obtaining subsequent and separate FCC approvals for intentional radiation.

The MRF24WG0MA/MB module has been labeled with its own FCC ID number, and if the FCC ID is not visible when the module is installed inside another device, then the outside of the finished product into which the module is installed must also display a label referring to the enclosed module. This exterior label can use wording as follows:

Contains Transmitter Module FCC ID: W70MRF24WG0MAMB

or

Contains FCC ID:

W7OMRF24WG0MAMB

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

(1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

A user's manual for the product should include the following statement:

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy, and if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- · Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.1.1 RF EXPOSURE

All transmitters regulated by FCC must comply with RF exposure requirements. OET Bulletin 65, *Evaluating Compliance with FCC Guidelines for Human Exposure to Radio Frequency Electromagnetic Fields*, provides assistance in determining whether proposed or existing transmitting facilities, operations or devices comply with limits for human exposure to Radio Frequency (RF) fields adopted by the Federal Communications Commission (FCC). The bulletin offers guidelines and suggestions for evaluating compliance.

If appropriate, compliance with exposure guidelines for mobile and unlicensed devices can be accomplished by the use of warning labels and by providing users with information concerning minimum separation distances from transmitting structures and proper installation of antennas.

The following statement must be included as a CAUTION statement in manuals and OEM products to alert users of FCC RF exposure compliance:

To satisfy FCC RF Exposure requirements for mobile and base station transmission devices, a separation distance of 20 cm or more should be maintained between the antenna of this device and persons during operation. To ensure compliance, operation at closer than this distance is not recommended.

The antenna(s) used for this transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

If the MRF24WG0MA/MB module is used in a portable application (i.e., the antenna is less than 20 cm from persons during operation), the integrator is responsible for performing Specific Absorption Rate (SAR) testing in accordance with FCC rules 2.1091.

3.1.2 APPROVED EXTERNAL ANTENNA TYPES

To maintain modular approval in the United States, only the antenna types that have been tested shall be used. It is permissible to use different antenna manufacturer provided the same antenna type and antenna gain (equal to or less than) is used.

Testing of the MRF24WG0MB module was performed with the antenna types listed in Table 2-2 in **Section 2.0 "Circuit Description"**.

3.1.3 HELPFUL WEB SITES

Federal Communications Commission (FCC): http://www.fcc.gov.

3.2 Canada

The MRF24WG0MA/MB module has been certified for use in Canada under Industry Canada (IC) Radio Standards Specification (RSS) RSS-210 and RSS-Gen. Modular approval permits the installation of a module in a host device without the need to recertify the device.

Labeling Requirements for the Host Device (from Section 3.2.1, RSS-Gen, Issue 3, December 2010):

The host device shall be properly labeled to identify the module within the host device.

The Industry Canada certification label of a module shall be clearly visible at all times when installed in the host device, otherwise the host device must be labeled to display the Industry Canada certification number of the module, preceded by the words "Contains transmitter module", or the word "Contains", or similar wording expressing the same meaning, as follows:

Contains transmitter module IC: 7693A-24WG0MAMB

User Manual Notice for License-Exempt Radio Apparatus (from Section 7.1.3 RSS-Gen, Issue 3, December 2010):

User manuals for license-exempt radio apparatus shall contain the following or equivalent notice in a conspicuous location in the user manual or alternatively on the device or both:

This device complies with Industry Canada license-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

3.2.1 APPROVED EXTERNAL ANTENNA TYPES

Transmitter Antenna (from Section 7.1.2 RSS-Gen, Issue 3, December 2010):

The MRF24WG0MB module can only be sold or operated with antennas with which it was approved. Transmitter may be approved with multiple antenna types. An antenna type comprises antennas having similar in-band and out-of-band radiation patterns. Testing shall be performed using the highest gain antenna of each combination of transmitter and antenna type for which approval is being sought, with the transmitter output power set at the maximum level. Any antenna of the same type having equal or lesser gain as an antenna that had been successfully tested with the transmitter, will also be considered approved with the transmitter, and may be used and marketed with the transmitter.

When a measurement at the antenna connector is used to determine RF output power, the effective gain of the device's antenna shall be stated, based on measurement or on data from the antenna manufacturer. For transmitters of output power greater than 10 milliwatts, the total antenna gain shall be added to the measured RF output power to demonstrate compliance to the specified radiated power limits. User manuals for transmitters shall display the following notice in a conspicuous location:

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante.

The above notice may be affixed to the device instead of displayed in the user manual.

User manuals for transmitters equipped with detachable antennas shall also contain the following notice in a conspicuous location:

This radio transmitter (identify the device by certification number, or model number if Category II) has been approved by Industry Canada to operate with the antenna types listed below with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante.

Immediately following the above notice, the manufacturer shall provide a list of all antenna types approved for use with the transmitter, indicating the maximum permissible antenna gain (in dBi) and required impedance for each.

Approved external antenna types for the MRF24WG0MA/MB module are listed in Table 2-2 in **Section 2.0 "Circuit Description"**.

3.2.2 HELPFUL WEB SITES

Industry Canada: http://www.ic.gc.ca/

3.3 Europe

The MRF24WG0MA/MB module conforms to the emission standards summarized in Table 3-1. The module tests can be applied toward product certification and Declaration of Conformity (DoC).

Note: To maintain conformance tested ETSI standards, the module shall not be modified.

The European Standards do not provide a modular approval similar to the USA (FCC) and Canada (IC). However, the completed compliance testing can be used as part of the customer's application for product compliance approvals. The module test report data can be used as part of the customer's product test plan and can significantly lower customer's compliance burden.

Depending on the end application, additional testing may be required. The integrator is responsible for testing the end product for any additional compliance requirements that become necessary with this module installed (for example, digital device emission, PC peripheral requirements and so on) in the specific country where end device is marketed).

3.3.1 EXTERNAL ANTENNA REQUIREMENTS

European conformance testing was performed using the antenna types listed in Table 2-2 in **Section 2.0** "Circuit Description".

3.3.2 HELPFUL WEB SITES

A document that can be used as a starting point in understanding the use of Short Range Devices (SRD) in Europe is the European Radio Communications Committee (ERC) Recommendation 70-03 E, which can be downloaded from the European Radio Communications Office (ERO) at: http://www.ero.dk/.

Additional helpful web sites are:

 Radio and Telecommunications Terminal Equipment (R&TTE):

http://ec.europa.eu/enterprise/rtte/index en.htm

 European Conference of Postal and Telecommunications Administrations (CEPT): http://www.cept.org

 European Telecommunications Standards Institute (ETSI):

http://www.etsi.org

 European Radio Communications Office (ERO): http://www.ero.dk

TABLE 3-1: EMISSIONS STANDARDS TESTED

	Test Method		
	rest wethou		
EN 300 328 V1.7.1 (2006-10)	4.3.1	Maximum Transmit Power	5.7.2
EN 300 328 V1.7.1 (2006-10)	4.3.2	Maximum EIRP Spectral Density	5.7.3
EN 300 328 V1.7.1 (2006-10)	4.3.3	Frequency Range	5.7.4
EN 300 328 V1.7.1 (2006-10)	4.3.6	Transmitter Spurious Emissions	5.7.5
EN 300 328 V1.7.1 (2006-10)	4.3.7	Receiver Spurious Emissions	5.7.6

3.4 Other Regulatory Jurisdictions

Should other regulatory jurisdiction certification be required by the customer, or the customer need to recertify the module for other reasons, a certification utility is available. The utility runs on a Window's PC and utilizes a USB to SPI converter to interface to the MRF24WG0MA/MB module. In order to use the utility, the MRF24WG0MA/MB module must be out of reset and not accessed by the system host. That is, the SPI signals to the MRF24WG0MA/MB module must be tristate, with Reset and Hibernate deasserted. The following signals will need to be brought from the MRF24WG0MA/MB module for connection to the PC (through the USB adapter):

- SDO
- SDI
- CS
- SCK
- INT
- GND

For further regulatory Certification Utility and documentation, contact your local Microchip salesperson.

3.5 Wi-Fi[®] Alliance

Wi-Fi Alliance Certification focuses on interoperability testing of devices based on 802.11 standards.

Historically, when the certification process and programs were developed by Wi-Fi Alliance members, the vast majority of the 802.11 clients were PC-centric, and certification testing adequately addressed those types of devices. In subsequent years, the number of Wi-Fi devices that are not PC-centric has grown significantly.

These non-standard devices, as a class of products, have been dubbed Application Specific Devices (ASDs) by the Wi-Fi Alliance. ASDs are 802.11 devices, for example clients or access points (APs), which cannot be tested under a standard Alliance test plan because they do not comply with the standard test configuration and/or because they are designed to perform a specific application. Examples include, but are not limited to: bar code scanners, pagers, recording devices, monitoring equipment, and cable modems.

The APs or clients that are used to validate ASD compliance (from the standard test bed) will meet all of the requirements specified in the applicable System Interoperability Test Plans (referred to as the "standard test plan"), unless specifically exempted. The MRF24WG0MA/MB modules are in the ASD category.

The modules are certified under Wi-Fi 802.11 with WPA2, WPA, and WEP System Interoperability ASD Model Test Plan with Test Engine For IEEE 802.11a, b, and g Devices (Version 1.0).

NOTES:

4.0 ELECTRICAL CHARACTERISTICS

TABLE 4-1: DIGITAL ELECTRICAL CHARACTERISTICS (NOMINAL CONDITIONS: 25°C, VDD = 3.3V)

Parameters	Min	Тур	Max	Units
VIL (Input low voltage)	-0.3	_	0.8	V
Vін (Input high voltage)	2	_	5.5	V
Vol (Output low voltage)	_	_	0.4	V
Voн (Output high voltage)	2.4	_	_	V
IOL (Output low level current at VoL Max)	_	8.5	_	mA
Юн (Output high level current at VOH Min)	_	15.4	_	mA

TABLE 4-2: ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Parameters	Min	Max	Notes
Storage Temperature	-40°C	+125°C	_
VDD	0V	3.60V	_
VIN on SDI, CS, SCK	-0.3V	3.60V	_

Note 1: The listed Absolute Maximum Ratings are not meant for functional operation. Operation exceeding these levels is not guaranteed, and may reduce the operating life of the component.

TABLE 4-3: RECOMMENDED OPERATING CONDITIONS

Parameters	Min	Тур	Max	Units
Ambient Temperature	-40	_	+85	Degrees Celsius
VDD – for FCC and IC	2.80	3.3	3.60	Volts

TABLE 4-4: CURRENT CONSUMPTION⁽¹⁾ (NOMINAL CONDITIONS: 25°C, VDD = 3.3V)

Parameters	Min	Тур	Max	Units	Conditions
IDD, Hibernate = 3.3V	_	0.1	_	μA	_
IDD, Power Save (software enabled)	1	4 ⁽²⁾	_	mA	_
IDD, RX on, Receive @ -91 dBm with 1 Mbps modulated signal at antenna port		85	_	mA	_
IDD, TX on, 802.11b, +18 dBm	_	237	_	mA	Measured at 11 Mbps
IDD, TX on, 802.11g, +16 dBm	_	226	_	mA	Measured at 6 Mbps

- Note 1: Current Consumption values represent Typical Peak currents, and the measured current conditions were done with 85% duty cycle modulated signal. Wi-Fi applications typically operate at less than 85% TX duty cycle. TX current is dependent on such criteria as transmit power setting, and transmit data rate and bandwidth being used. RX current is affected by connection distance.
 - **2:** Power Save current is current consumed during periods of "stand-by" between DTIM beacons. The module will awake 2 ms before a DTIM and turn on its receiver, and possibly its transmitter (if data is available).

TABLE 4-5: RECEIVER AC CHARACTERISTICS⁽¹⁾

Parameters	Min	Тур	Max	Units
Flo	2412	_	2484	MHz
RX Min Input Level Sensitivity, 1 Mbps, 8% PER	_	-95	_	dBm
RX Min Input Level Sensitivity, 2 Mbps, 8% PER	_	-88	_	dBm
RX Max Input Level (Power), 1 Mbps, 8% PER	_	-4	_	dBm
RX Max Input Level (Power), 2 Mbps, 8% PER	_	-4	_	dBm

Note 1: Nominal conditions: 25°C, VDD = 3.3V, Flo = 2437 MHz, measurements at antenna port.

TABLE 4-6: TRANSMITTER AC CHARACTERISTICS⁽¹⁾

Parameters	Min	Тур	Max	Units
Flo	2412	_	2484	MHz
Average Pout (transmit spectrum mask compliant)	_	+18	_	dBm
Average Pout gain step resolution from +5 to +10 dBm(2)	_	0.5	_	dB
Average Pout gain step resolution from -5 to Max. (2)	_	1.0	_	dB

Note 1: Nominal conditions: 25°C, VDD = 3.3V, Flo = 2437 MHz, 2 Mbps. modulated signal measured at antenna port.

^{2:} Gain step control is not calibrated. Steps are shown for planning purposes only.

FIGURE 4-1: SPI INPUT TIMING

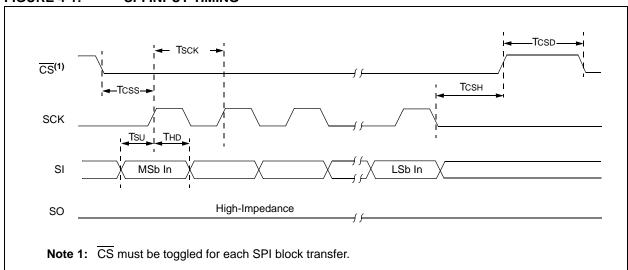


FIGURE 4-2: SPI OUTPUT TIMING

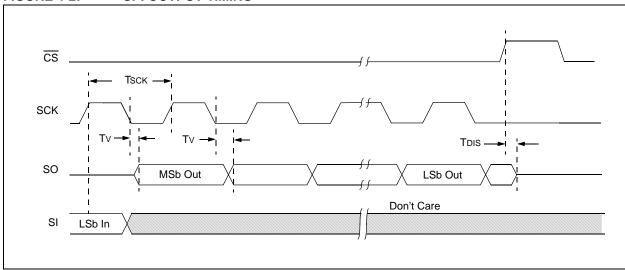


TABLE 4-7: SPI INTERFACE AC CHARACTERISTICS

Symbol	Parameters	Min	Max	Units
Tsck	SCK Period	40	_	ns
TCSD	CS High time	50	_	ns
Tcss	CS Setup time	50	_	ns
Тсѕн	CS Hold time	50	_	ns
Tsu	SDI Setup time	10	_	ns
THD	SDI Hold time	10	_	ns
Tv	SDO Valid time	_	15	ns

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (July 2012)

This is the initial released version of this document.

NOTES:

THE MICROCHIP WEB SITE

Microchip provides online support via our WWW site at www.microchip.com. This web site is used as a means to make files and information easily available to customers. Accessible by using your favorite Internet browser, the web site contains the following information:

- Product Support Data sheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- General Technical Support Frequently Asked Questions (FAQ), technical support requests, online discussion groups, Microchip consultant program member listing
- Business of Microchip Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

CUSTOMER CHANGE NOTIFICATION SERVICE

Microchip's customer notification service helps keep customers current on Microchip products. Subscribers will receive e-mail notification whenever there are changes, updates, revisions or errata related to a specified product family or development tool of interest.

To register, access the Microchip web site at www.microchip.com. Under "Support", click on "Customer Change Notification" and follow the registration instructions.

CUSTOMER SUPPORT

Users of Microchip products can receive assistance through several channels:

- · Distributor or Representative
- · Local Sales Office
- · Field Application Engineer (FAE)
- · Technical Support
- · Development Systems Information Line

Customers should contact their distributor, representative or field application engineer (FAE) for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document.

Technical support is available through the web site at: http://microchip.com/support

READER RESPONSE

It is our intention to provide you with the best documentation possible to ensure successful use of your Microchip product. If you wish to provide your comments on organization, clarity, subject matter, and ways in which our documentation can better serve you, please FAX your comments to the Technical Publications Manager at (480) 792-4150.

Please list the following information, and use this outline to provide us with your comments about this document.

TO: RE:	Technical Publications Manager Reader Response	Total Pages Sent
From	n: Name	
	CompanyAddress	
	City / State / ZIP / Country	
	Telephone: ()	FAX: ()
	ication (optional):	
	ld you like a reply?YN	
Devi	ce: MRF24WG0MA/MB	Literature Number: DS00000A
Ques	stions:	
1. \	What are the best features of this document?	
2. H	How does this document meet your hardware a	nd software development needs?
3. [Do you find the organization of this document ea	asy to follow? If not, why?
4. V	What additions to the document do you think wo	ould enhance the structure and subject?
-		
5. \ -	What deletions from the document could be ma	de without affecting the overall usefulness?
-		
6. I	Is there any incorrect or misleading information	(what and where)?
7. H	How would you improve this document?	
-		
_		

PRODUCT IDENTIFICATION SYSTEM

To order parts, including industrial, or obtain information, for e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO. Device	M Module	X Module Type	T Tape and Reel	-X Temperature Range	Exa a)	nmples: MRF24WG0MA-I/RM = Industrial Temp
Device		G0MA/MB; e 2.7V to 3.6V				
Temperature Rang	ge I = -40°C	to +85°C (Indu	strial Temperati	ure)		

Note the following details of the code protection feature on Microchip devices:

- · Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our
 knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data
 Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

Trademarks

The Microchip name and logo, the Microchip logo, dsPIC, KEELOQ, KEELOQ logo, MPLAB, PIC, PICmicro, PICSTART, PIC³² logo, rfPIC and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

FilterLab, Hampshire, HI-TECH C, Linear Active Thermistor, MXDEV, MXLAB, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Application Maestro, chipKIT, chipKIT logo, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, dsSPEAK, ECAN, ECONOMONITOR, FanSense, HI-TIDE, In-Circuit Serial Programming, ICSP, Mindi, MiWi, MPASM, MPLAB Certified logo, MPLIB, MPLINK, mTouch, Omniscient Code Generation, PICC, PICC-18, PICDEM, PICDEM.net, PICkit, PICtail, REAL ICE, rfLAB, Select Mode, Total Endurance, TSHARC, UniWinDriver, WiperLock and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2012, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

Printed on recycled paper.

ISBN:

QUALITY MANAGEMENT SYSTEM CERTIFIED BY DNV = ISO/TS 16949=

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.



Worldwide Sales and Service

AMERICAS

Corporate Office

2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7200

Fax: 480-792-7277 Technical Support:

http://www.microchip.com/

support

Web Address: www.microchip.com

Atlanta

Duluth, GA

Tel: 678-957-9614 Fax: 678-957-1455

Boston

Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca, IL

Tel: 630-285-0071 Fax: 630-285-0075

Cleveland

Independence, OH Tel: 216-447-0464 Fax: 216-447-0643

Dallas

Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit

Farmington Hills, MI Tel: 248-538-2250 Fax: 248-538-2260

Indianapolis

Noblesville, IN Tel: 317-773-8323 Fax: 317-773-5453

Los Angeles

Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608

Santa Clara

Santa Clara, CA Tel: 408-961-6444 Fax: 408-961-6445

Toronto

Mississauga, Ontario,

Canada

Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office

Suites 3707-14, 37th Floor Tower 6, The Gateway Harbour City, Kowloon Hong Kong

Tel: 852-2401-1200 Fax: 852-2401-3431

Australia - Sydney

Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing

Tel: 86-10-8569-7000 Fax: 86-10-8528-2104

China - Chengdu

Tel: 86-28-8665-5511 Fax: 86-28-8665-7889

China - Chongqing

Tel: 86-23-8980-9588 Fax: 86-23-8980-9500

China - Hangzhou

Tel: 86-571-2819-3187 Fax: 86-571-2819-3189

China - Hong Kong SAR

Tel: 852-2401-1200 Fax: 852-2401-3431

China - Nanjing

Tel: 86-25-8473-2460 Fax: 86-25-8473-2470

China - Qingdao

Tel: 86-532-8502-7355 Fax: 86-532-8502-7205

China - Shanghai

Tel: 86-21-5407-5533 Fax: 86-21-5407-5066

China - Shenyang

Tel: 86-24-2334-2829 Fax: 86-24-2334-2393

China - Shenzhen

Tel: 86-755-8203-2660 Fax: 86-755-8203-1760

China - Wuhan

Tel: 86-27-5980-5300 Fax: 86-27-5980-5118

China - Xian

Tel: 86-29-8833-7252 Fax: 86-29-8833-7256

China - Xiamen

Tel: 86-592-2388138 Fax: 86-592-2388130

China - Zhuhai

Tel: 86-756-3210040 Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore

Tel: 91-80-3090-4444 Fax: 91-80-3090-4123

India - New Delhi

Tel: 91-11-4160-8631 Fax: 91-11-4160-8632

India - Pune

Tel: 91-20-2566-1512 Fax: 91-20-2566-1513

Japan - Osaka

Tel: 81-66-152-7160 Fax: 81-66-152-9310

Japan - Yokohama

Tel: 81-45-471- 6166 Fax: 81-45-471-6122

Korea - Daegu

Tel: 82-53-744-4301 Fax: 82-53-744-4302

Korea - Seoul

Tel: 82-2-554-7200 Fax: 82-2-558-5932 or 82-2-558-5934

Malaysia - Kuala Lumpur

Tel: 60-3-6201-9857 Fax: 60-3-6201-9859

Malaysia - Penang

Tel: 60-4-227-8870 Fax: 60-4-227-4068

Philippines - Manila

Tel: 63-2-634-9065 Fax: 63-2-634-9069

Singapore

Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan - Hsin Chu

Tel: 886-3-5778-366 Fax: 886-3-5770-955

Taiwan - Kaohsiung

Tel: 886-7-536-4818 Fax: 886-7-330-9305

Taiwan - Taipei

Tel: 886-2-2500-6610 Fax: 886-2-2508-0102

Thailand - Bangkok

Tel: 66-2-694-1351 Fax: 66-2-694-1350

EUROPE

Austria - Wels

Tel: 43-7242-2244-39 Fax: 43-7242-2244-393

Denmark - Copenhagen

Tel: 45-4450-2828 Fax: 45-4485-2829

France - Paris

Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany - Munich

Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Italy - Milan

Tel: 39-0331-742611 Fax: 39-0331-466781

Netherlands - Drunen

Tel: 31-416-690399 Fax: 31-416-690340

Spain - Madrid

Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

UK - Wokingham Tel: 44-118-921-5869 Fax: 44-118-921-5820

11/29/11